

17. (Amended) A method of manufacturing a light emitting device comprising:

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irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light, thereby sublimating a vapor deposition material adhering to the component; and
exhausting the sublimated vapor deposition material.

Please add the following new claims:

Rule 126(a) ~~27~~ 18. (New) The method according to claim 16 wherein said at least one selected from the group consisting of the infrared light, UV-light, and visible light is radiated by using a light source provided in the film-forming chamber.

~~28~~ 19. (New) The method according to claim 16 wherein an irradiation surface of said at least one selected from the group consisting of the infrared light, UV-light, and visible light is in a rectangular or oblong shape.

B2 ~~29~~ 20. (New) The method according to claim 16 further comprising a step of supplying a halogen containing gas into the film-forming chamber during sublimating the vapor deposition material.

~~30~~ 21. (New) The method according to claim 16 further comprising a step of forming a plasma during exhausting.

~~31~~ 22. (New) The method according to claim ³⁰~~21~~ wherein said plasma is an oxygen plasma.

~~32~~ 23. (New) The method according to claim 16 wherein the vapor deposition material comprises an organic light emitting material.

~~33~~ 24. (New) The method according to claim 17 wherein said at least one selected from the group consisting of the infrared light, UV-light, and visible light is radiated by using a light source provided in the film-forming chamber.

~~34~~ 25. (New) The method according to claim 17 wherein an irradiation surface of said at least one selected from the group consisting of the infrared light, UV-light, and visible light is in a rectangular or oblong shape.

~~35~~ 26. (New) The method according to claim 17 further comprising a step of supplying a halogen containing gas into the film-forming chamber during sublimating the vapor deposition material.

~~36~~ 27. (New) The method according to claim 17 further comprising a step of forming a plasma during exhausting.

~~37~~ 28. (New) The method according to claim ³⁶27 wherein said plasma is an oxygen plasma.

~~38~~ 29. (New) The method according to claim 17 wherein the vapor deposition material comprises an organic light emitting material.

~~39~~ 30. (New) A method of manufacturing a display device comprising:
providing a substrate by a substrate holder in a film formation chamber;
forming a film comprising an organic material over the substrate by vapor deposition in the film formation chamber wherein said organic material is simultaneously deposited on said substrate holder;

removing said substrate from said reaction chamber after forming said film;
heating said organic material deposited on said substrate holder in said film formation chamber to vaporize said organic material;
exhausting the vaporized organic material from said film formation chamber.

40 ~~31~~³⁹ (New) The method according to claim ~~30~~³⁹ wherein said film comprising an organic material is a light emitting layer.

41 ~~32~~³⁹ (New) The method according to claim ~~30~~³⁹ further comprising a step of supplying a halogen containing gas into the film formation chamber during heating said organic material.

42 ~~35~~³⁹ (New) The method according to claim ~~30~~³⁹ further comprising exposing the vaporized organic material to a plasma.

62 43 ~~34~~ (New) A method of manufacturing a display device comprising:
providing a substrate by a substrate holder in a film formation chamber wherein an adhesion preventing shield is provided between said substrate and an inner wall of the film formation chamber;

forming a film comprising an organic material over the substrate by vapor deposition in the film formation chamber wherein said organic material is simultaneously deposited on said adhesion preventing shield;

removing said substrate from said reaction chamber after forming said film;
heating said adhesion preventing shield to vaporize said organic material deposited on said adhesion preventing shield;
exhausting the vaporized organic material from said film formation chamber.

44 ~~35~~⁴³ (New) The method according to claim ~~34~~⁴³ wherein said film comprising an organic material is a light emitting layer.